




Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STM32F101VET6	9G1L*414XXX2	B	959	19-04-2019
	Amount	UoM	Unit type	ST ECOPACK Grade
	681.44	mg	Each	ECOPACK® 2
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant ( in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable; if coating is used or other bulk termination	Matte Tin(Sn)	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFP	14x14x1.4	100	L Bend	
Comment	Package : 1L LQFP 100 14x14x1.4 1 0086901			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : Chinese RoHS , references : SJT 11364 – 2014 and GBT 26572 – 2014				
Query				Response
1 - Product(s) requires marking for the presence of restricted substances and must be marked with an Environmental Protection Use Period under China's Measures for Administration of the control of pollution by Electronic Information Products				FALSE
2 - Product(s) is eligible for marking with the e code under China's Measures for Administration of the control of pollution by Electronic Information Products				FALSE
Hasardous substance				
Lead (Pb)	Cadmium (Cd)	Mercury (Hg)	Hexavalent Chromium (Cr VI)	PBB & PBDE
O	O	O	O	O

QueryList : REACH-27th June 2018				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				TRUE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration :						Mfr Item Name	9G1L*414XXX2				5999999.0	0.0
note : Substance present with less 0.001mg will not be declared in this document												
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or dies	M-011 Other inorganic materials	18.257	mg	supplier	die	Silicon (Si)	7440-21-3		17.500	mg	958536	25681
				supplier	metallization	Aluminium (Al)	7429-90-5		0.051	mg	2793	75
				supplier	metallization	Copper (Cu)	7440-50-8		0.257	mg	14077	377
				supplier	metallization	Cobalt (Co)	7440-48-4		0.048	mg	2629	70
				supplier	metallization	Titanium (Ti)	7440-32-6		0.014	mg	767	21
				supplier	metallization	Tungsten (W)	7440-33-7		0.028	mg	1534	41
				supplier	Passivation	Silicon Nitride	12033-89-5		0.034	mg	1862	50
				supplier	Passivation	Silicon Oxide	7631-86-9		0.325	mg	17801	477
				supplier	ALLOY	Copper (Cu)	7440-50-8		147.008	mg	940282	215731
LEADFRAME	M-011 Other inorganic materials	156.345	mg	supplier	ALLOY	Iron (Fe)	7439-89-6		3.621	mg	23160	5314
				supplier	ALLOY	Iron Phosphide (Fe2P)	1310-43-6		0.045	mg	288	66
				supplier	ALLOY	Zinc (Zn)	7440-66-6		0.181	mg	1158	266
				supplier	SPOT	Silver (Ag)	7440-22-4		5.490	mg	35112	8056
DIE ATTACH	M-011 Other inorganic materials	2.904	mg	supplier	GLUE	Silver (Ag)	7440-22-4		2.483	mg	855000	3644
				supplier	GLUE	Dodecyl acrylate	2156-97-0		0.073	mg	25000	107
				supplier	GLUE	methylene diacrylate	42594-17-2		0.232	mg	80000	341
				supplier	GLUE	Diglycidylphenyl glycidyl ether	13561-08-5		0.058	mg	20000	85
				supplier	GLUE	Isobornyl Methacrylate	7534-94-3		0.029	mg	10000	43
BONDING WIRE	M-011 Other inorganic materials	1.534	mg	supplier	BONDING WIRE	dimethylbenzyl peroxide	80-43-3		0.029	mg	10000	43
				supplier	BONDING WIRE	Silver (Ag)	7440-22-4		1.480	mg	965000	2172
				supplier	BONDING WIRE	Gold (Au)	7440-57-5		0.008	mg	5000	11
ENCAPSULATION	M-011 Other inorganic materials	496.943	mg	supplier	BONDING WIRE	Palladium (Pd)	7440-05-3		0.046	mg	30000	68
				supplier	MOLDING COMPOUND	Silica, vitreous	60676-86-0		429.563	mg	864366	369626
				supplier	MOLDING COMPOUND	Epoxy Resin	Proprietary		37.158	mg	74798	54529
				supplier	MOLDING COMPOUND	Phenol Resin	Proprietary		24.772	mg	49865	36353
				supplier	MOLDING COMPOUND	3-Mercaptopropyl trimethoxysilane	4420-74-0		2.477	mg	4987	3635
				supplier	MOLDING COMPOUND	Quartz	14808-60-7		1.486	mg	2992	2181
				supplier	MOLDING COMPOUND	Carbon black	1333-86-4		1.486	mg	2992	2181
FINISHING	M-011 Other inorganic materials	5.457	mg	supplier	COATING	Tin (Sn)	7440-31-5		5.457	mg	1000000	8008